

ALPHA SLS 65

No Clean Flux

ALPHA SLS 65 was specifically developed to eliminate the tendency for solder balling and solder bridging – two defects which are normally associated with the use of the chip wave. Of all low solids (<4% solids), no-clean fluxes, SLS 65 exhibits the lowest tendency for solder ball generation over a wide variety of solder masks. SLS 65 should be considered for use by any assembler who has board designs which are sensitive to solder bridging, performs pin testing, and / or whose specification requires an extremely low frequency of solder balls.

DESCRIPTION

ALPHA SLS 65 is an active, low solids, no-clean flux. It is formulated with a proprietary mixture of organic activators. Several proprietary additives are formulated into SLS 65, which act to reduce the surface tension between the solder resist and the solder, thereby dramatically reducing the tendency of solder ball generation. The formulation of SLS 65 is also designed to be more thermally stable, thereby reducing the occurrence of solder bridging.

FEATURES & BENEFITS

- Thermally stable activators provide the lowest solder bridging in a low-solids, no-clean flux.
- Reduces the surface tension between solder and resist to provide the lowest solder ball frequency of any low solids, no-clean flux.
- Very low level of non-tacky residue to reduce interference with pin testing and exhibit no visible residue.
- Cleaning is not required which reduces operating costs.
- Bellcore Compliant for long term electrical reliability.

APPLICATION

PREPARATION – In order to maintain consistent soldering performance and electrical reliability, it is important to begin the process with circuit boards and components that meet established requirements for solderability and ionic cleanliness. It is suggested that assemblers establish specifications on these items with their suppliers and that suppliers provide Certificates of Analysis with shipments and / or assemblers perform incoming inspection. A common specification for the ionic cleanliness of incoming boards and components is $0.77\mu\text{g}/\text{cm}^2$ ($5\mu\text{g}/\text{in}^2$) maximum, as measured by an Omegameter with heated solution. Care should be taken in handling the circuit boards throughout the process. Boards should always be held at the edges. The use of clean, lint-free gloves is also recommended. When switching from one flux to another, the use of a new foam stone is recommended (for foam fluxing). Conveyors, fingers and pallets should be cleaned. BIOACT SC-10 Solvent Cleaner has been found very useful for these cleaning applications. When foam fluxing; do not use hot fixtures or pallets. Hot fixtures or pallets will deteriorate the foam head.

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FLUX APPLICATION – SLS 65 is formulated to be applied by foam, wave or spray methods. When foam fluxing, the foam fluxer should be supplied with compressed air which is free of oil and water. Keep the flux tank full at all times. The flux level should be maintained 25-40mm (1-1½”) above the top of the stone. Adjust the air pressure to produce the optimum foam height with a fine, uniform foam head. A uniform coating of flux is essential to successful soldering. When using the foam or wave method of application, an air knife is recommended after the fluxing operation, An air knife will help ensure that the flux is uniformly distributed across the board and will remove the excess flux. When spray fluxing, the uniformity of the coating can be visually checked by running a piece of cardboard over the spray fluxer or by processing a board-sized piece of tempered glass through the spray and then through the preheat section.

GENERAL GUIDELINES FOR MACHINE SETTINGS

OPERATING PARAMETER	TYPICAL LEVEL
Amount of flux to be applied	Foam, Wave 155 - 232µ/cm ² of solids Spray: 70 – 125µ/cm ² of solids
When foam fluxing: Foam Stone Pore Size Distance that top of stone is submerged below flux Foam Fluxer Chimney Opening	20 - 50µm 25 – 38 10 – 13mm
When foam fluxing, use an air knife: Air knife hole diameter: Distance between holes Distance from Fluxer to Air knife Air knife angle back toward fluxer from perpendicular	1 – 1.5mm 4 – 5mm 10 – 15cm 3° - 5°
Topside Preheat Temperature	100°C - 120°C
Bottom side Preheat Temperature	about 35°C higher than topside
Maximum ramp rate of topside temperature (to avoid component damage)	2°C/second maximum
Conveyor angle	5°C - 8°C (6°C most common)
Conveyor speed	1.00 – 2.00 meters/minute
Contact time in the solder (includes chip wave and primary wave)	1.5 – 3.5 seconds (2½ - 3 seconds most common)
Solder pot temperature	235°C - 260°C
These are general guidelines, which have proven to yield excellent results; however, depending upon your equipment, components and circuit boards; your optimal settings may be different. In order to optimize your process, it is recommended to perform a designed experiment, optimizing the most important variables (amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation).	

FLUX SOLIDS CONTROL – If foam, wave, or rotary drum spray fluxing, the flux solids will need to be controlled via thinner addition to replace evaporative losses of the flux solvent. As with any flux with less than 5% solids content, specific gravity is **not** an effective measurement for assessing and controlling the solids content. Monitoring and controlling the acid number is recommended for maintaining the solids content. The acid number should be controlled between 17 and 19. When operating the foam fluxer continuously, the acid number should be checked every two to four hours.

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Over time, debris and contaminants will accumulate in recirculating type flux applicators. For consistent soldering performance, dispose of spent flux every 40 hours of operation. After emptying the flux, the reservoir and foam stone should be thoroughly cleaned with flux thinner.

RESIDUE REMOVAL – ALPHA SLS65 is a no-clean flux and the residues are designed to be left on the board. However, if desired, ALPHA SLS65 residues can be removed with ALPHA 2110 Saponifier.

TOUCH-UP/REWORK – Use of Cleanline Write Flux Applicator with NR205 flux, and Fluitin 1532 cored solder wire is recommended for hand soldering applications.

TECHNICAL SPECIFICATIONS

Parameters	Typical Values
Appearance	Clear, colorless liquid
Solids content, wt/wt	2.3%
Acid number (mg KOH/g)	18
Specific Gravity @ 25°C (77°F)	0.801 ± 0.003
Pounds per gallon	6.8
Flash point (T.C.C)	12°C (53°F)

Parameters/Test Method	Typical Values
pH (5% aqueous solution)	3.4
Recommended Thinner	425 Thinner
Shelf life	12 months
Container size availability	Various
Bellcore TR-NWT-000078, Issue 3 complaint	Yes
IPC J-STD-004 Designation	ORL0

CORROSION TESTING

Corrosion Testing	Requirements	Results
Silver Chromate Paper Test	No detection of Halide	Passes
Copper Mirror Test	No complete removal of copper	Passes
IPC Copper Corrosion test	NONE	Type L0

SURFACE INSULATION RESISTANCE (all value in ohms)		
Test Condition	Requirements	Results
Bellcore “Comb-Down” – uncleaned	1.0 x 10 ¹¹ minimum	4.5 x 10 ¹¹
Bellcore “Comb-Up” – Uncleaned	1.0 x 10 ¹¹ minimum	1.4 x 10 ¹¹
Bellcore Control Board	2.0 x 10 ¹¹ minimum	9.3 x 10 ¹¹
IPC J-STD-004A Comb down – Uncleaned	1.0 x 10 ⁸ minimum	2.1 x 10 ⁹
IPC J-STD-004A Comb up – Uncleaned	1.0 x 10 ⁸ minimum	1.5 x 10 ⁹
IPC J-STD-004A Control Board	1.0 x 10 ⁹ minimum	1.1 x 10 ¹⁰
Bellcore Test Condition (per TR-NWT-000078, Issue 3): 35°C/85%RH/120 hours/-48 volts, measurement @ 100V/25 mil lines/50 mil spacing.		
IPC Test Condition (per J-STD-004A): 85°C/85%RH/168 hours/-50V, measurement @ 100V/IPC B-24 board (0.4mm lines, 0.5mm spacing)		

HEALTH & SAFETY

Please refer to the Material Safety Data Sheet as the primary source of health and safety information. Inhalation of the flux solvent and volatilized activator fumes, which are generated at soldering temperatures, may cause headaches, dizziness and nausea. Suitable fume extraction equipment should be used to remove the flux from the work area. An exhaust at the exit end of the wave solder machine may also be needed to completely capture the fumes.

Observe precautions during handling and use. Suitable protective clothing should be worn to prevent the material from coming in contact with skin and eyes. ALPHA SLS65 flux contains a highly flammable solvent with a flashpoint of 12°C (53°F). The flux must not be used near open flames or near non-flameproof electrical equipment.

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